



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01409	REV: E1	SUN REV: Not In VersionControl
	TID #: 01409		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/8/2017	1:16:01 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01409	REV: E1	SVN REV: Not In VersionControl
	TID #: 01409		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/8/2017 1:16:03 PM		TEXAS INSTRUMENTS

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